

Technical Data Sheet

MODEL NO: B5050RGB4-6815

Features:

• Package in 8mm tape on 7" diameter reel

• Compatible with automatic placement equipment

• Compatible with reflow solder process

Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP/GaAs	Red	
InGaN	Green	Water transparent
InGaN	Blue	

Electrical/Optical Characteristics(Ta=25 $^{\circ}$ C)

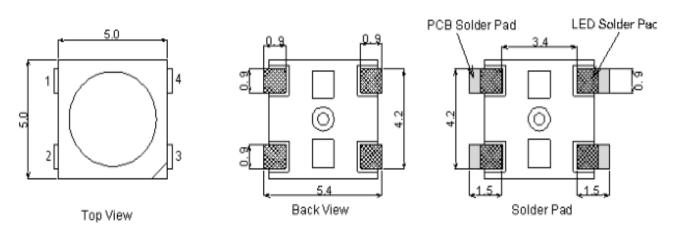
Parameter	Test	Symbol -			Unit		
Farameter	Condition			Min	Тур	Max	Ullit
			R		18		
Spectral half bandwidth	IF=20mA	$\triangle \lambda$	G		33		nm
			В		30		
		λО	R	620	625	630	nm
Dominant wavelength	IF=20mA		G	515	520	525	
			В	460	465	470	
	IF=20mA	VF	R	2.0	2.1	2.2	V
Forward voltage			G	3.0	3.2	3.4	
			В	3.0	3.2	3.4	
	IF=20mA	lv	R	400		500	mcd
Luminous intensity			G	800		1200	
			В	200		400	
Viewing angle at 50% lv	IF=10mA	2 0 1/2			120		Deg
Reverse current	V _R =5V	lr			10		μА

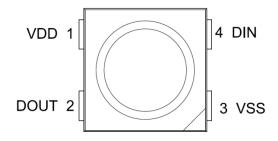


Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	,	Unit		
		R	G	В	
Power dissipation	Pd	75 111 111			mW
Forward current	lF	30			mA
Reverse voltage	V R	5			V
Operating temperature range	Тор	-40 ~+85			$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+90			$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/8 duty f=1kHz)	I FP	125			mA

PACKAGING DIMENSIONS (mm):



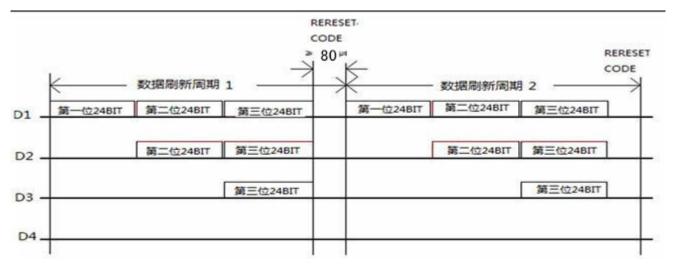




Absolute maximum ratings		Top light Emitting Diode							
Parameter	Symbol	Rat		Unit					
Input range	VIN	3.0-7.5		V					
Logic input voltage	VI	-0.5~5.5		V					
Operating Temperature			Тор	-40~+85		°C			
Storage Temperature	Tstg	-50~+150		$^{\circ}$ C					
ESD pressure	VESD	4K		V					
Electrical parameters TA=-20°C ~70°C VDD=4.5~5.5V VSS=0V									
parameters	Symbol	Min	Typical	Max	Unit	Test condition			
Chip input voltage	Vin		5	7.5	V				
Chip internal power supply voltage	VDD		5.2		V				
R/G/B Port pressure	Vds			9	V				
R/G/B	lo		12		ma				
	VIH	0.7VDD			V	VDD=5.0V			
The signal input flip threshold	VIL			0.3VDD	V	VDD=5.0V			
PWM Frequency	FPWM		1.2		KHZ				
Static power consumption	IDD		1.0		ma				

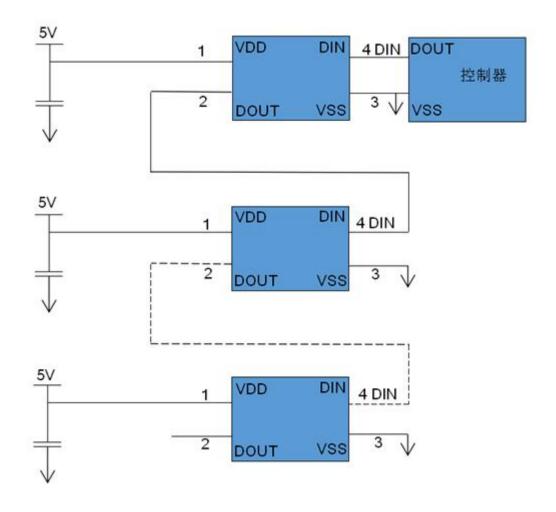


Data transmission mode (Ta=25°C):



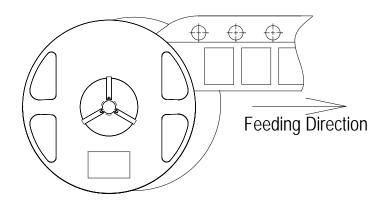
4bit

R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4
G3	G2	G1	G0	В7	В6	В5	В4	В3	В2	B1	В0

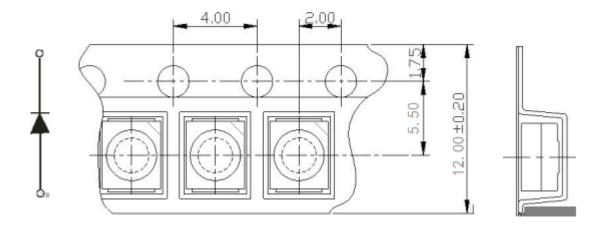




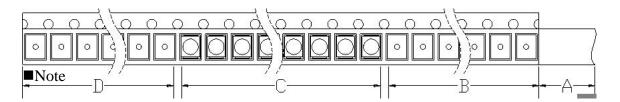
■Feeding Direction



■Dimensions of Tape (Unit: mm)



■Arrangement of Tape



- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two.
- 3. The cathode is oriented towards the tape sprocket hole;
- 4. 1,000pcs/Reel

Precautions For Use:

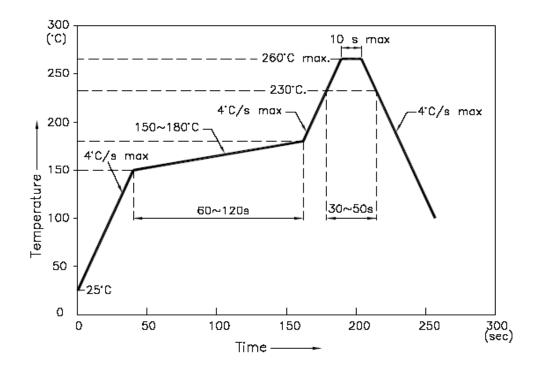
Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time





NOTES:

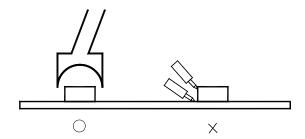
- 1. We recommend the reflow temperature $245\,^{\circ}\text{C}(\pm 5\,^{\circ}\text{C})$.the maximum soldering temperature should be limited to $260\,^{\circ}\text{C}$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

■Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow , solder etc.